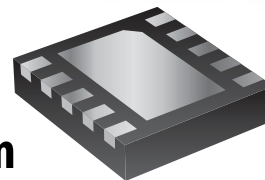


# Product Change Notification

## CHIP DIODES

February, 2013



### Additional Assembly/Test Location for TVS Diode DFN Packages

To support our fast growing demand, secure continuity of supply and provide maximum flexibility to our customers, Bourns is adding an additional assembly/test location in China for the assembly/test of the DFN package for our TVS diode products. The affected part number using the DFN package is the [Model CDDFN10-3304N](#) TVS/Steering Diode Array.

#### Product Labeling:

The product marking is unchanged except for the country code information.

#### Identification of the Changed Product:

Bourns maintains traceability back to source wafer lots and assembly sites for all products.

#### Impact on Form, Fit, Function and Reliability:

The package outline dimensions will continue to meet the current Bourns data sheet. Product ratings and electrical characteristics are unaffected by the change. There is no impact on form, fit, function, quality or reliability. For qualification information and results, please see the data below.

#### Implementation Dates are as Follows:

- Last date of manufacture of existing product: Bourns has no plans to discontinue assembly and test of products at its existing subcontract sites.
- Deliveries to customers from new site may occur from July, 2013 onward.
- First date code from new site: 1313

#### New Assembly/Test Location Qualification:

##### Qualification Information:

All Products	
Die Technology	TVS Diode Products
Product Name	CDDFN10-3304N
Top Metal	Al
Back Metal	AlNiAu
Assembly Site	China
Pins/Package	DFN 10
Mold Compound	CEL9220
Die Attach	8006N
Bond Wire	Au
L/F Material	Copper
Marking	Laser
Termination Finish	Matte Sn (Pb Free)

**Qualification Results:**

Test Plan					
					Lot 1
Stress Test	Conditions	Standard	Method	SS/Acc	SS/fail
Moisture Induced Stress Sensitivity		J-STD-020	-	Level 1	154/0
HTRB	125 °C, 1000 h	MIL STD 750	1048	22/0	22/0
HTST	150 °C, 1000 h	J-STD-22	A103	22/0	22/0
PCT	121 °C / 100 % RH, 2 atm, 168 h	J-STD-22	A102	22/0	22/0
TCT	65 / +150 °C, 500 cs	J-STD-22	A104	22/0	22/0
Solderability	8 h Steam	JESD22-	B102E	5/0	5/0
Dimensions	Data Sheet	MIL STD 883	2025	5/0	5
Flammability	3 mm	UL 94-V0			
W/Bond Pull Strength	-	MIL STD 883	2011	76/0	76/0
Die Shear	-	MIL STD 883	2019	5/0	5/0
X-Ray	-	MIL STD 883	2012	5/0	5/0

*Samples subjected are preconditioned according to JESD22-A113 (260 °C).*

If you have any questions or need additional information, please feel free to contact [Customer Service/Inside Sales](#).